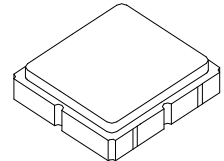


- Low-loss UHF SAW Filter
- Surface-mount 3.0 x 3.0 x 1.3 mm Package
- Complies with Directive 2002/95/EC (RoHS)



**SF2203E**

**834 MHz  
SAW Filter**



**SM3030-6**

**Absolute Maximum Ratings**

Rating	Value	Units
Input Power Level	15	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +95	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$F_C$			834		MHz
Maximum Insertion Loss, 819 to 849 MHz	$IL_{MAX}$				4	dB
Amplitude Ripple, 819 to 849 MHz					2	dB <sub>P-P</sub>
Return Loss, 819 to 849 MHz			10			dB
Attenuation Referenced to 0 dB:						
10 to 660 MHz			30			dB
660 to 710 MHz			25			
710 to 760 MHz			20			
864 to 869 MHz			15			
894 to 934 MHz			20			
934 to 990 MHz			25			
990 to 2600 MHz			25			
Source Impedance	$Z_S$			50		Ω
Load Impedance	$Z_L$			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	933, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

**Electrical Connections**

Connection	Terminals
Input	5
Output	2
Ground	All Others

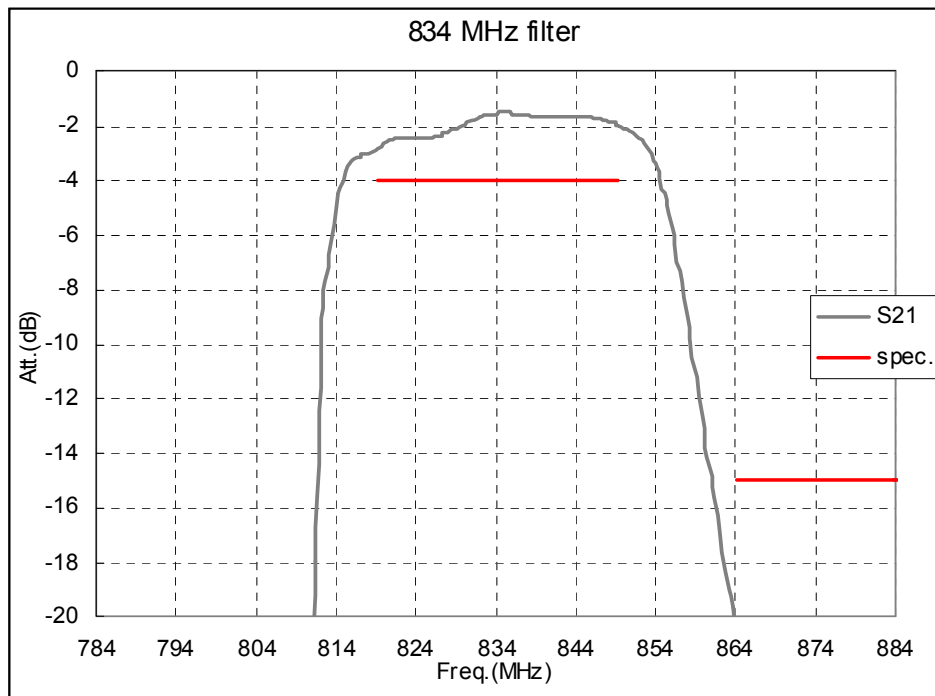


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

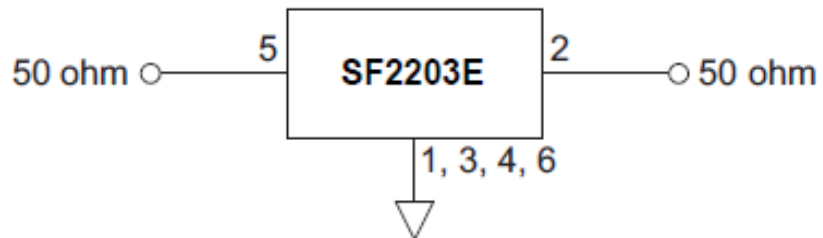
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

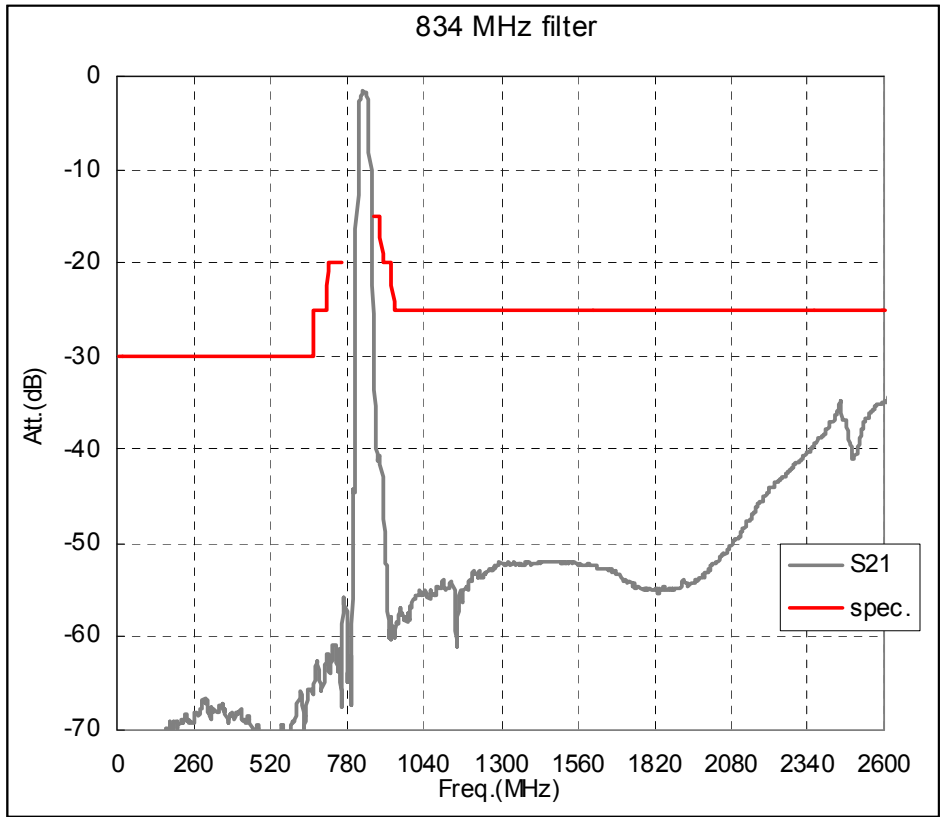
## Filter Passband Response



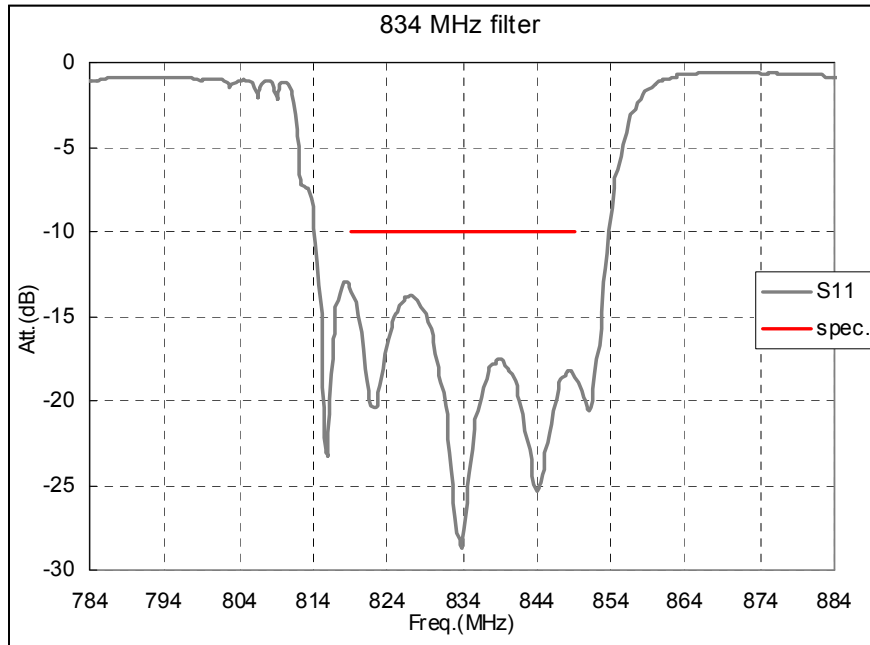
## Filter Test Circuit



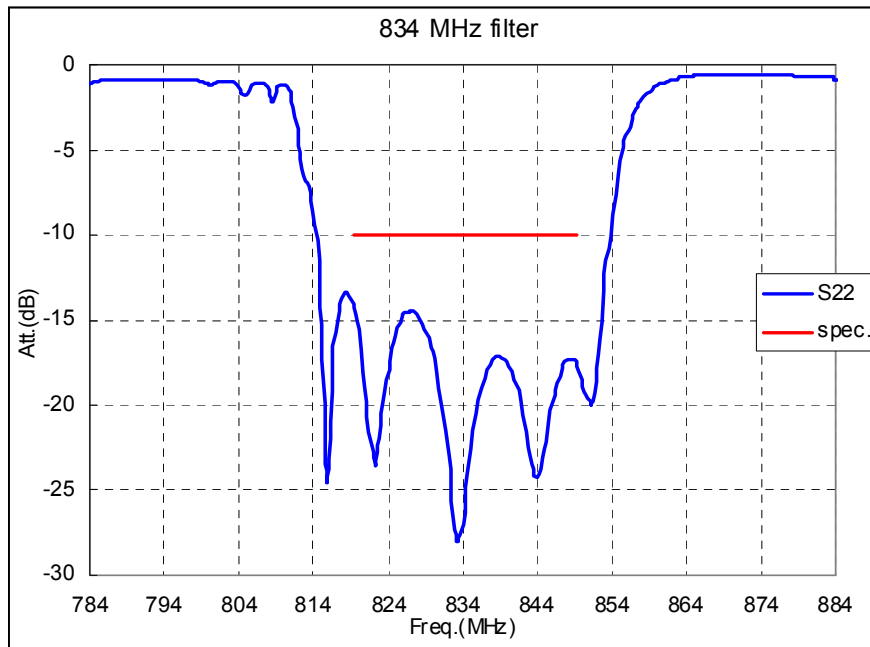
# Filter Broadband Response, 0 to 2600 MHz



## Filter S<sub>11</sub> Plot

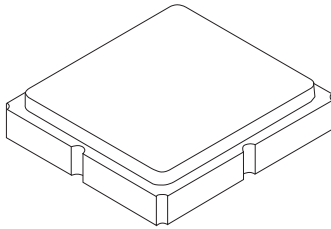


## Filter S<sub>22</sub> Plot



# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

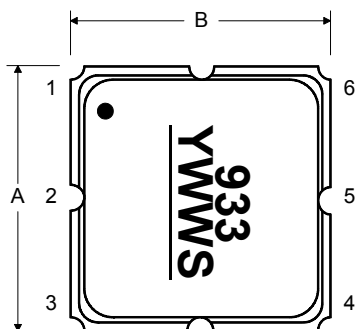
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

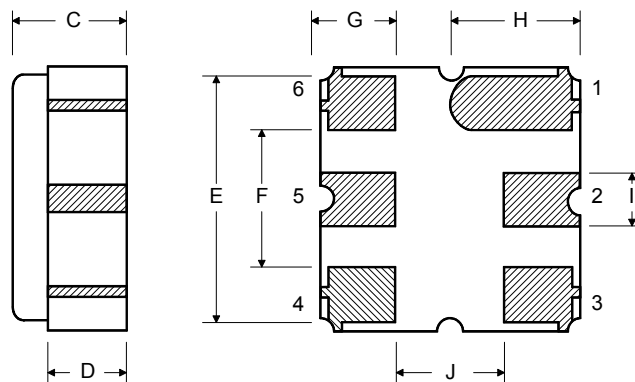
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic
Pb Free	

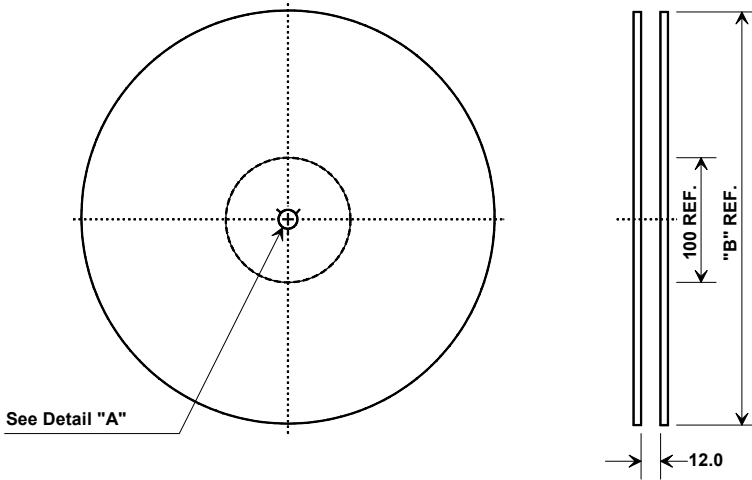
### TOP VIEW



### BOTTOM VIEW

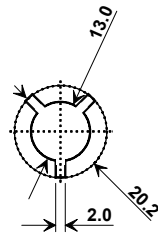


## Tape and Reel Specifications



Tape and Reel Standard per ANSI/EIA-481

"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



### COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm

